

Title (en)

CONNECTING STRUCTURE DEVICE BETWEEN ANALYSIS ELECTRONICS AND PROBE IN CYLINDER SYSTEMS

Title (de)

VORRICHTUNG VERBINDUNGSSTRUKTUR ZWISCHEN AUSWERTEELEKTRONIK UND SONDE IN ZYLINDERSYSTEMEN

Title (fr)

DISPOSITIF, STRUCTURE DE LIAISON ENTRE UN ÉQUIPEMENT ÉLECTRONIQUE D'ÉVALUATION ET UNE SONDE DANS DES SYSTÈMES À CYLINDRES

Publication

EP 3830895 A1 20210609 (DE)

Application

EP 19752438 A 20190730

Priority

- DE 102018212789 A 20180731
- EP 2019070495 W 20190730

Abstract (en)

[origin: WO2020025609A1] The invention relates to a device for guiding an electromagnetic wave within a cylinder head of a cylinder system, wherein the device comprises analysis electronics arranged in or on the cylinder head and a probe located in the cylinder head, as well as a connecting structure guiding the electromagnetic wave and arranged between the analysis electronics and the probe for versatile positioning of the analysis electronics, the connecting structure having a first signal connection (101, 201, 301, 401, 501a, 501b, 601, 701) for connection to the probe and a second signal connection (314, 514a, 514b, 714) for connection to the analysis electronics.

IPC 8 full level

H01P 5/02 (2006.01); **F15B 15/28** (2006.01); **H01P 5/08** (2006.01)

CPC (source: EP US)

F15B 15/2869 (2013.01 - US); **G01D 5/12** (2013.01 - US); **H01P 1/061** (2013.01 - US); **H01P 1/30** (2013.01 - US); **H01P 5/026** (2013.01 - EP); **H01P 5/085** (2013.01 - EP US); **H01P 5/183** (2013.01 - US); **F15B 15/2869** (2013.01 - EP); **H01R 4/02** (2013.01 - US); **H01R 4/48** (2013.01 - US); **H01R 4/56** (2013.01 - US); **H01R 12/58** (2013.01 - US); **H01R 24/50** (2013.01 - US)

Citation (examination)

EP 1752665 A1 20070214 - FESTO AG & CO [DE]

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

WO 2020025609 A1 20200206; CN 112740475 A 20210430; DE 102018212789 A1 20200206; EP 3830895 A1 20210609; US 2021332835 A1 20211028

DOCDB simple family (application)

EP 2019070495 W 20190730; CN 201980050782 A 20190730; DE 102018212789 A 20180731; EP 19752438 A 20190730; US 201917264585 A 20190730